

# Based Material Line Up



## S7045GHU/ S7045GHUB

### 1. CORE (C-STAGE)

Product	Thickness		ply-up	Dk		Df	
	(mm)	(mil)		1GHz	10GHz	1GHz	10GHz
S7045GHU	0.051	2	1x106	3.59	4.01	0.013	0.0153
	0.076	3	1x1080	3.77	4.19	0.012	0.0146
	0.102	4	1x3313	3.95	4.42	0.010	0.0138
	0.127	5	1x2116	3.97	4.43	0.010	0.0135
	0.152	6	2x1080	3.77	4.19	0.012	0.0146
	0.203	8	2x3313	3.95	4.42	0.010	0.0138
	0.254	10	2 x2116	3.97	4.43	0.010	0.0135
	0.381	15	3x2116	3.97	4.43	0.010	0.0135
	0.508	20	4x2116	3.97	4.43	0.010	0.0135
	0.635	25	5x2116	3.97	4.43	0.010	0.0135
	0.762	30	6x2116	3.97	4.43	0.010	0.0135
	1.016	40	8x2116	3.97	4.43	0.010	0.0135

### 2. PREPREG (B-STAGE)

Product	Glass style	RC%	Thickness (mm)	Dk		Df	
				1GHz	10GHz	1GHz	10GHz
S7045GHUB	106	72	0.051	3.59	4.01	0.013	0.0153
		77	0.064	3.48	3.88	0.013	0.0157

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	1080	64	0.076	3.77	4.19	0.012	0.0146
		68	0.086	3.68	4.10	0.012	0.0149
3313		56	0.102	3.95	4.42	0.010	0.0138
		60	0.117	3.86	4.27	0.011	0.0143
2116		55	0.127	3.97	4.43	0.010	0.0135
		59	0.145	3.88	4.30	0.011	0.0142

## 3. REMARK

- 1) Dk/Df at 1GHz measuring method: IPC TM-650 2.5.5.9;
- 2) Dk/Df at 10GHz measuring method: IEC61189-2-721 SPDR;
- 3) The above data is for reference only, but not guarantee value. SYTECH reserves the right for any update.